

Title (en)
METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS USING PARALLEL PROCESSES TO INTERCONNECT WITH SUBASSEMBLIES

Title (de)
VERFAHREN ZUR HERSTELLUNG VON LEITERPLATTEN MIT PARALLELVERFAHREN ZUR VERBINDUNG MIT BAUGRUPPEN

Title (fr)
PROCÉDÉS DE FABRICATION DE CARTES DE CIRCUIT IMPRIMÉ UTILISANT DES PROCESSUS PARALLÈLES EN VUE D'OBTENIR UNE INTERCONNEXION AVEC DES SOUS-ENSEMBLES

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Abstract (en)
[origin: WO2011136817A1] Methods of manufacturing printed circuit boards using parallel processes to interconnect with subassemblies are provided. In one embodiment, the invention relates to a method of manufacturing a printed circuit board including providing a core subassembly including at least one metal layer, providing a plurality of one-metal layer carriers after parallel processing each of the plurality of one-metal layer carriers, and attaching at least two of the plurality of one-metal layer carriers with each other and with the core subassembly.

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